



CP56 – 63/37 (Sn/Pb) Solder Balls  
CPG56 – Sn/Ag/Cu Solder Balls

SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	$\approx$	$\approx$	1.35	2
A <sub>1</sub>	0.15	0.20	0.25	
D/E	5.90	6.00	6.10	
D <sub>1</sub> /E <sub>1</sub>	4.50 BSC			
e	0.50 BSC			
phi b	0.25	0.30	0.35	
aaa	$\approx$	$\approx$	0.10	
ccc	$\approx$	$\approx$	0.20	
eee	$\approx$	$\approx$	0.15	
Z <sub>D</sub> /Z <sub>E</sub>	0.58	0.76	0.93	
M	10			

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994
2. SYMBOL "M" IS THE PIN MATRIX SIZE.

**56-BALL CHIP SCALE BGA 0.50mm PITCH (CP56/CPG56)**

## Revision History

The following table shows the revision history for this document.

Date	Version	Revision
06/22/04	1.2	Released to the Web.
07/09/08	1.3	Added fiducial mark feature on Bottom View and coplanarity dimension on Top View.